Arteris® IP FlexNoC® Interconnect and Resilience Package Supports Socionext's 5nm Automotive Chip Production

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Automotive chip design leader standardizes on Network-on-Chip (NoC) interconnect IP for multiple ISO 26262-compliant systems-on-chip (SoCs)

CAMPBELL, Calif. and YOKOHAMA, Japan– February 4, 2021 – Arteris IP, the world's leading supplier of innovative, silicon-proven network-on-chip (NoC) interconnect intellectual property, today announced that Socionext has implemented Arteris® FlexNoC® interconnect IP and the accompanying Resilience Package in multiple automotive chips, including an automotive SoC fabricated using 5nm semiconductor process technology.

> *We are able to more efficiently design large scale automotive chips because we are able to see early in the design process the layout impacts of our SoC and NoC architecture choices. This is especially important when using leading edge 5nm semiconductor process technologies. Furthermore, our SoC functional safety architecture has been enhanced by the novel technologies in the FlexNoC interconnect IP Resilience Package, allowing us to quickly tailor safety mechanisms for the desired ISO 26262 ASIL to meet our customers' demanding schedules."*
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> *Kaichi Yamashita, Head of the Automotive Business Unit,* ***Socionext***

The Socionext SoC design team are long-time Arteris IP licensees and expert users of the company's FlexNoC and Resilience Package interconnect IP products. The automotive chips implemented by Socionext will be used within applications that require mission-critical processing, including advanced driver assistance systems (ADAS) and autonomous driving systems.

"We are able to more efficiently design large scale automotive chips because we are able to see early in the design process the layout impacts of our SoC and NoC architecture choices. This is especially important when using leading edge 5nm semiconductor process technologies," said Koichi Yamashita, Head of the Automotive Business Unit at Socionext. "Furthermore, our SoC functional safety architecture has been enhanced by the novel technologies in the FlexNoC interconnect IP Resilience Package, allowing us to quickly tailor safety mechanisms for the desired ISO 26262 ASIL to meet our customers' demanding schedules."

"We are excited about the success Socionext has had using Arteris IP FlexNoC interconnect as the on-chip dataflow engine for their most complex 5nm automotive chips," said K. Charles Janac, President and CEO of Arteris IP. "Socionext's adoption of Arteris IP technology as the network-on-chip interconnect standard for their custom systems-on-chip is proof of the benefits of our state-of-the-art technology."

About Socionext

Socionext is a global, innovative enterprise that designs, develops and delivers System-on-Chip solutions to customers worldwide. The company is focused on technologies that drive today's leading-edge applications in consumer, automotive and industrial markets. Socionext combines world-class expertise, experience, and an extensive IP portfolio to provide exceptional solutions and ensure a better quality of experience for customers. Founded in 2015, Socionext Inc. is headquartered in Yokohama, and has offices in Japan, Asia, United States and Europe to lead its product development and sales activities. For more information, visit https://www.socionext.com.

About Arteris IP

Arteris IP provides network-on-chip (NoC) interconnect IP and IP deployment technology to accelerate system-on-chip (SoC) semiconductor development and integration for a wide range of applications from AI to automobiles, mobile phones, IoT, cameras, SSD controllers, and servers for customers such as Bosch, Baidu, Mobileye, Samsung, Toshiba and NXP. Arteris IP products include the Ncore® cache coherent and FlexNoC® non-coherent interconnect IP, the CodaCache® standalone last level cache, and optional Resilience Package (ISO 26262 functional safety), FlexNoC AI Package, and PIANO® automated timing closure capabilities. Customer results obtained by using Arteris IP products include lower power, higher performance, more efficient design reuse and faster SoC development, leading to lower development and production costs. For more information, visit www.arteris.com or find us on LinkedIn at https://www.linkedin.com/company/arteris.

Editorial Contact

Kurt Shuler
Arteris Inc.
+1 408 470 7300
kurt.shuler@arteris.com

Socionext Inc.
+81-45-568-1006
https://www.socionext.com/en/contact/